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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Mario Merlin et al.

Date: June 8, 2004

Serial No.: 10/057,399

Group Art Unit: 2827

Filed: January 25, 2002

Examiner: James M.. Mitchell

For: COMPRSSION ASSEMBLED ELECTRONIC PACKAGE HAVING A PLASTIC
MOLDED INSULATION RING

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUBMISSION OF FORMAL DRAWINGS

Sir:

Enclosed herewith please find seven (7) sheets of formal drawings containing Figures 1 through 7 for the above-identified application.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 8, 2004

Brendan J. Kennedy
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Signature

June 8, 2004
Date of Signature

Respectfully submitted,

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